

FABRICATION PARAMETERS:

THICKNESS: SILKSCREEN: SOLDERMASK: COPPER WEIGHT: DESIGN TYPE: MIN TRACE/GAP: LAYER COUNT: 0.062 BOTH BOTH 2 OZ (EXT) /1 OZ (INT) MIX 0.005/0.005 6 LAYERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:

2. BASE LAMINATE:

3. SOLDERMASK:

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE. BONDING MATERIALS AND SOLDEMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-790 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL-94V-0. PLASTIC SHEET, LAMINATED METAL CLOD, TWO SIDES, BASE MATERIAL NEWA TYPE FR-4 GLASS EROXY RESIN, COPPER-CLAD IN ACCORDIANCE WITH BLAYER STACK-UP, COMPLIANT WITH LOOP FREE PROCESS.
SOLDEMANSK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDEMASK IN ACCORDANCE WITH IPC-SW-840.
NULSE REQUIREM PLATTING, SEE HOLE CHART, TO HAVE 1 0Z. (0.0014) MIN. THK MIN. THICK COPPER. 4. PLATING:

HOLES REQUIRING PLAITING, SEE MOLE CHARM, 1 VI. 1.

FILTICK COPPER.

PLATE WITH RAHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu,
WITH BMA FLUX, 0.005' -/ 0.0003' THICK MIN ALL EXPOSED AREAS
AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.

IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.

BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK),
LOCATION OFTIONAL.

PCE BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
PCES VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS
INSTRUMENTS UPON COMPLETION OF PURCHASE GROPER.

HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.

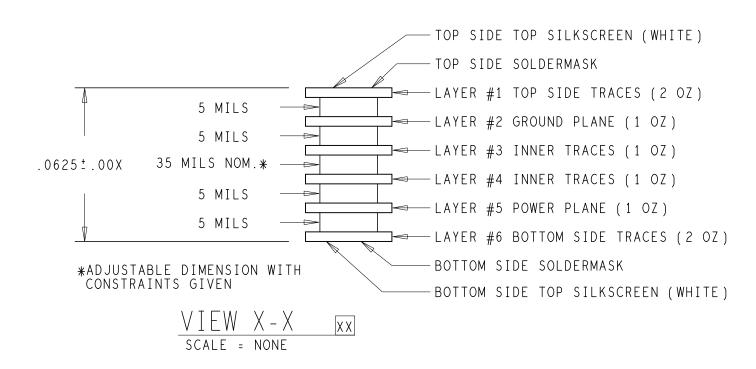
ANY METAL IN BOBDER AREA INCLIDING PART NUMBER, DATECODE AND/OR REVISION LETTERS

MUST BE COVERED WITH SOLDEMASK. 5. FINISH:

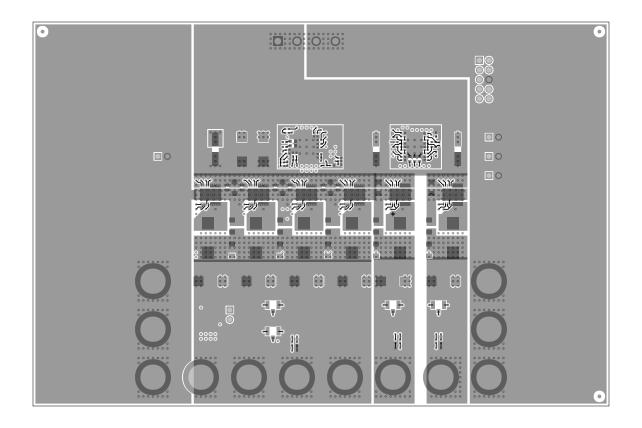
6. LEGEND: 7. MARKINGS:

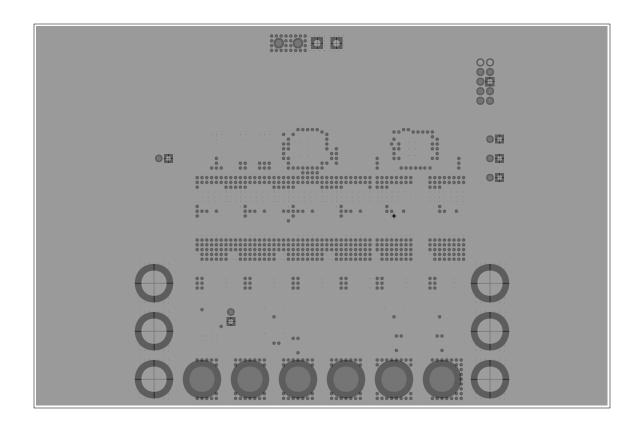
MUST BE COVERED WITH SOLDERMASK.

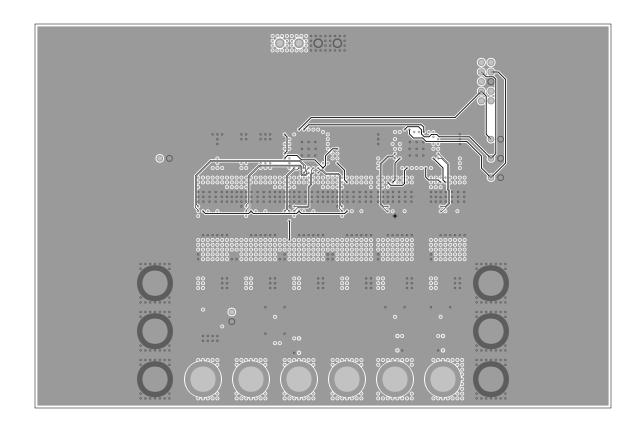
12. PROCESS CHANGES:NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

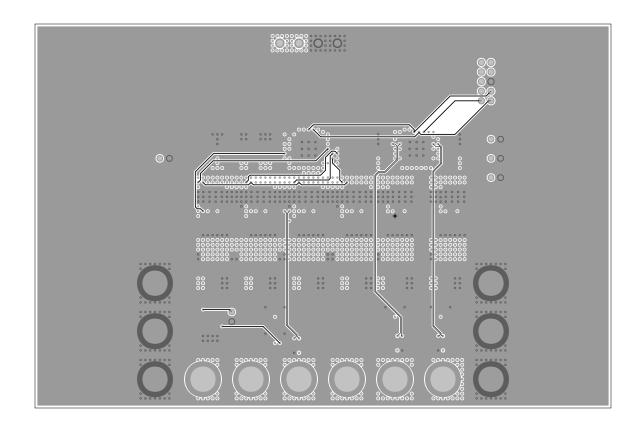


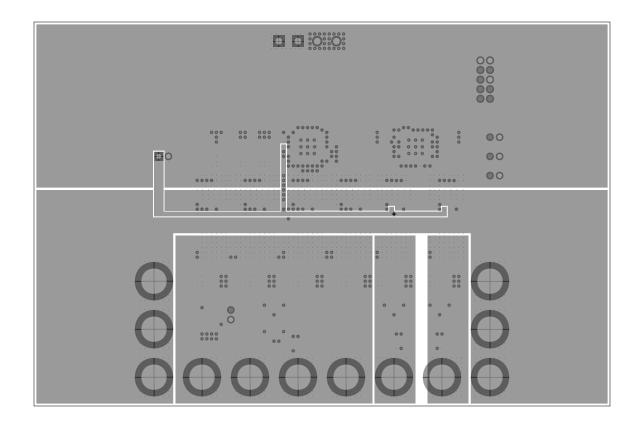
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
0	10.0	+3.0/-3.0	PLATED	1112
+	50.0	+3.0/-3.0	PLATED	10
f	55.0	+3.0/-3.0	PLATED	10
*	70.0	+3.0/-3.0	PLATED	4
\Diamond	263.0	+3.0/-3.0	PLATED	12

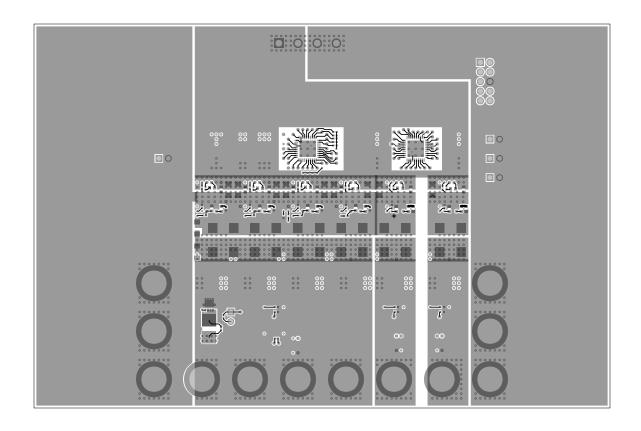


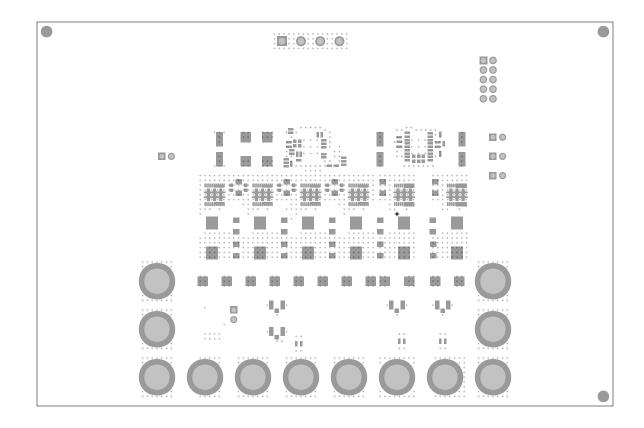


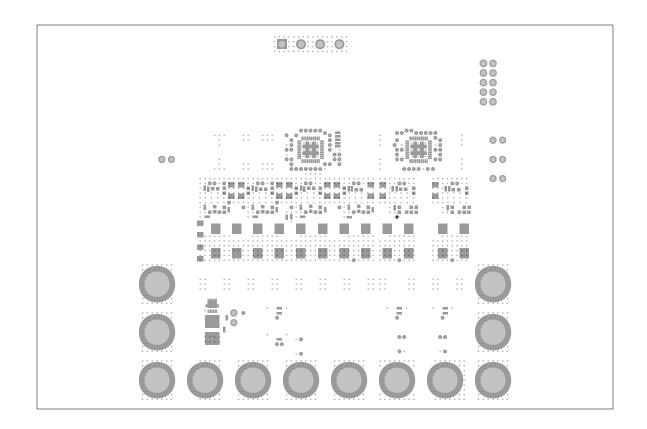


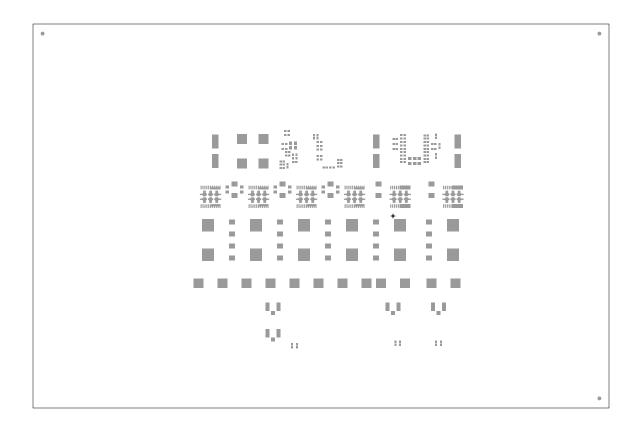


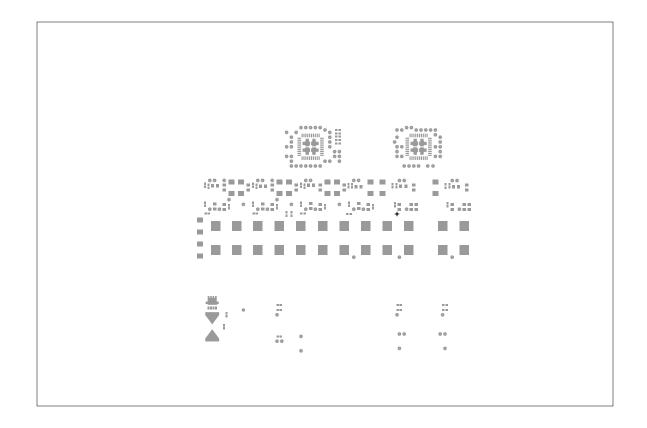


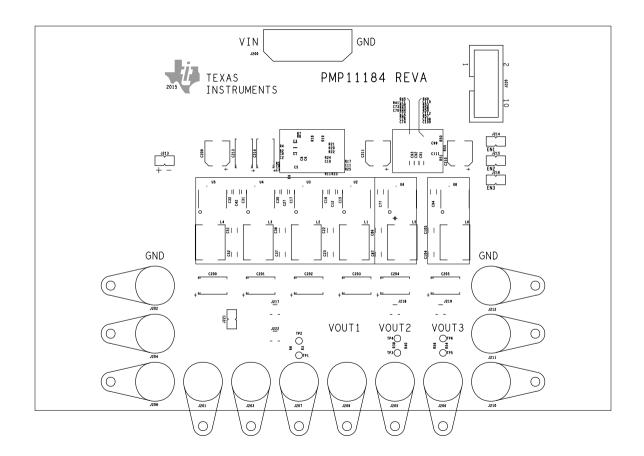


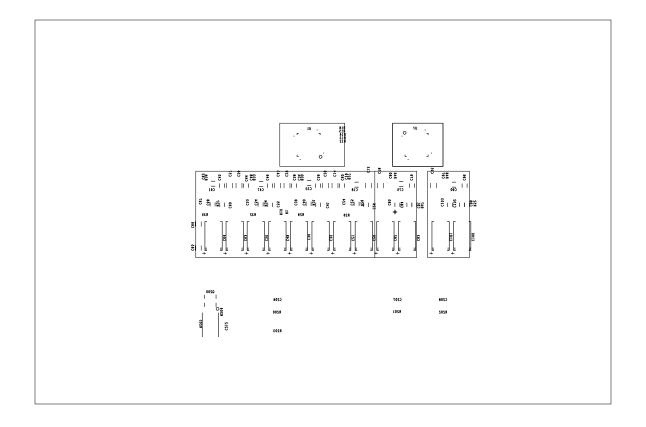












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